

Product Change Notification



Microsemi Corporation

April 4, 2016

Product/Process Change Notification No: 1400A00240

Change Classification: Minor

Subject: Updating package standoff, maximum package height and lead thickness on [WF2M16-XDAX5](#), [WMF2M8-XDAX5](#)

Description of Change: Correction of mechanical dimensions

Datasheet changes are as follows:-

1. Package standoff changes from 0.51mm (0.020") +/- 0.13mm (0.005") to 1.02mm (0.040") +/- 0.18mm (0.007")
2. Max package height changes from 3.43mm (0.135") to 2.87mm (0.113")
3. Lead thickness changes from 0.18mm (0.007") +/- 0.05mm (0.002") to 0.20mm (0.008") +/- 0.05mm (0.002")

Reason for Change: Error in previous package drawing

Application Impact: None, documentation update only.

Method of Identifying Changed Product: Not applicable.

Products Affected by this Change: [WF2M16-XDAX5](#), [WMF2M8-XDAX5](#)

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Regards,

Microsemi Corporation